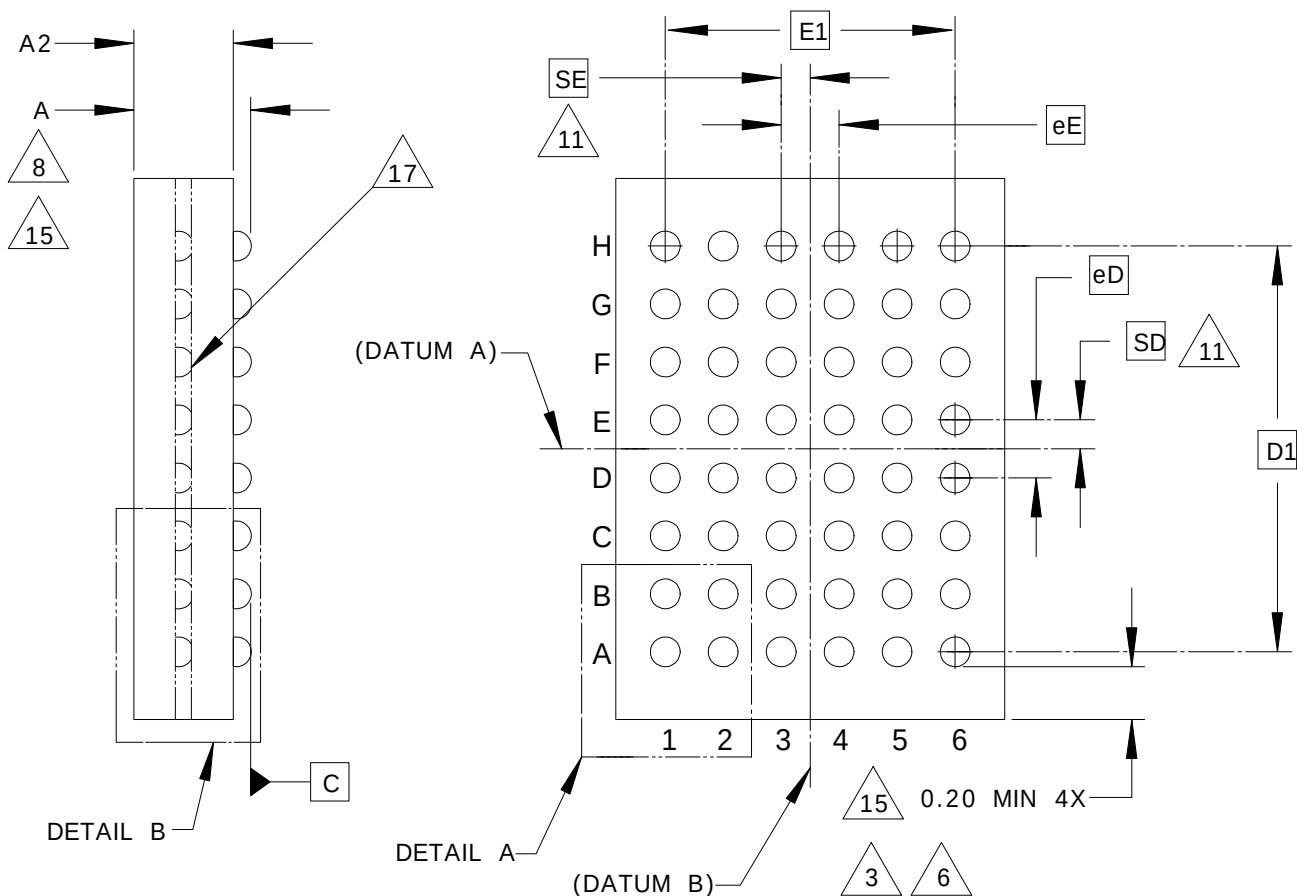
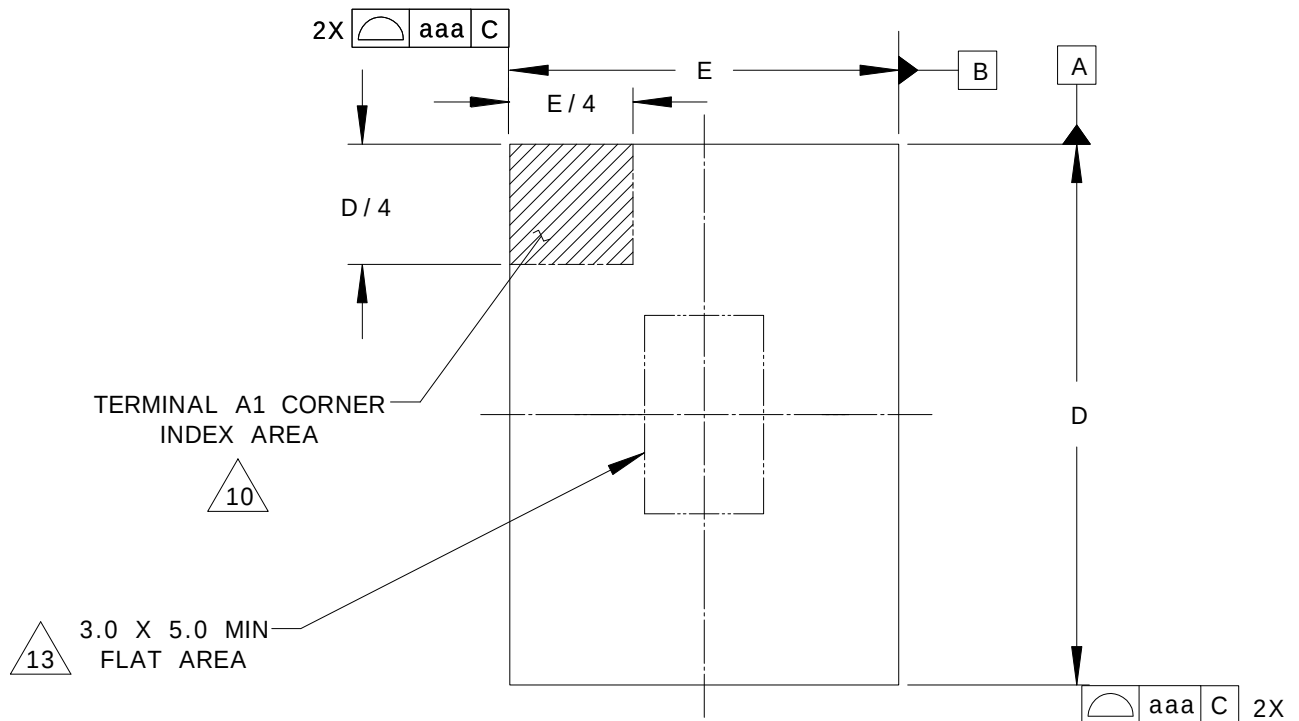




JEDEC
SOLID STATE
PRODUCT OUTLINE

THIS REGISTERED OUTLINE HAS BEEN PREPARED AND PUBLISHED BY THE JEDEC JC - 11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USE IN THE ELECTRONICS INDUSTRY. CHANGES ARE LIKELY TO OCCUR

TITLE: RECTANGULAR DIE - SIZE,
STACKED BALL GRID ARRAY FAMILY,
DUAL PITCH

PACKAGE DESIGNATOR:
AFR - PDSB

ISSUE:
A

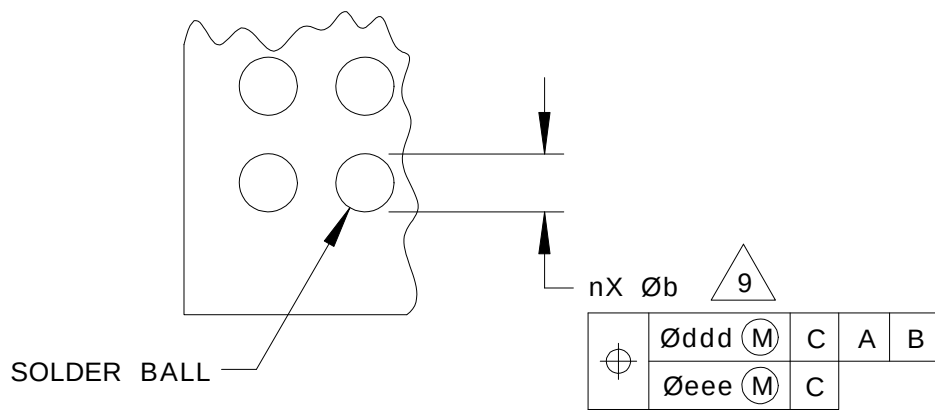
DATE:
11/05



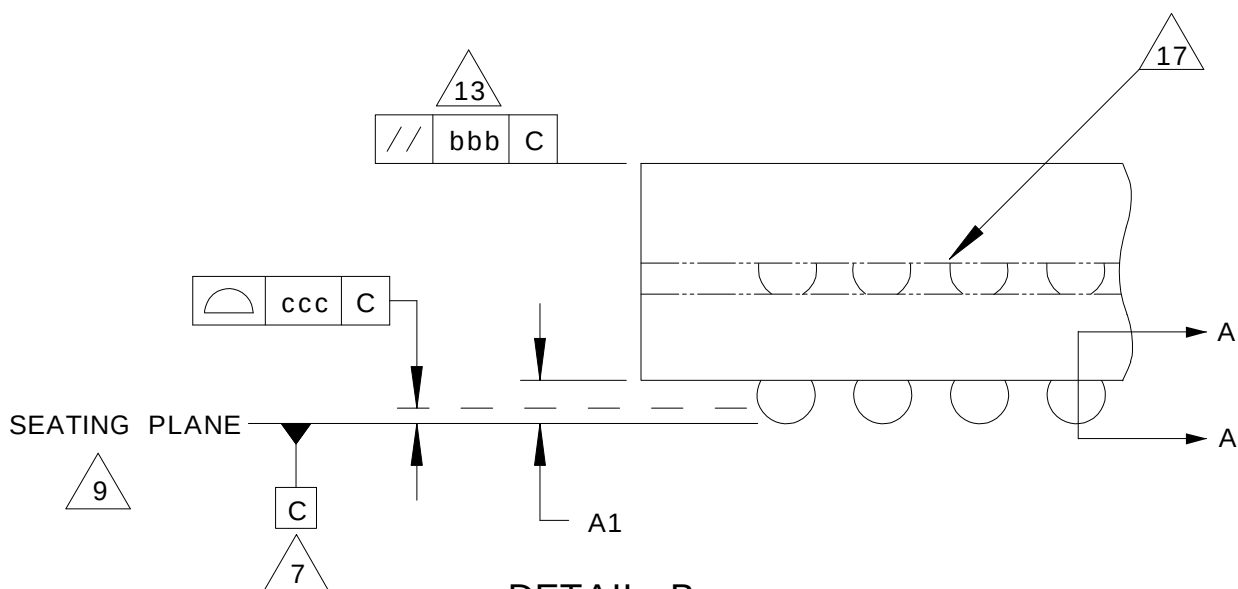
MO 264

PAGE:

1 OF 5



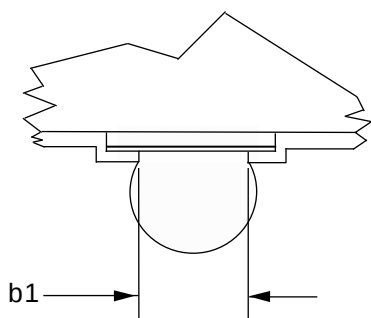
DETAIL A



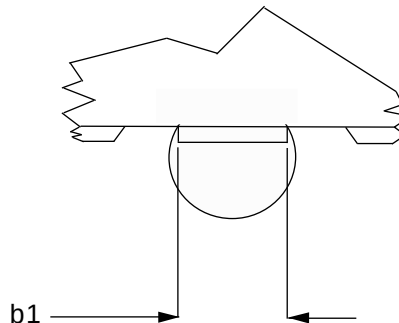
DETAIL B
(ROTATED 90° CW)

SECTION A - A

Type 1 SMD
(Solder Mask Defined)



Type 2 NSMD
(Not Solder Mask Defined)



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